

<b>PATENT ASSIGNMENT COVER SHEET</b>
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EPAS ID: PAT4698961

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
DROR HURWITZ	06/05/2014
ALEX HUANG	06/05/2014
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	ZHUHAI ADVANCED CHIP CARRIERS & ELECTRONIC SUBSTRATE SOLUTIONS TECHNOLOGIES CO. LTD.
<b>Street Address:</b>	FOUNDER PCB INDUSTRY PARK
<b>Internal Address:</b>	QIANWU, DOUMEN
<b>City:</b>	ZHUHAI
<b>State/Country:</b>	CHINA
<b>Postal Code:</b>	519173
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	15409221
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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<b>Correspondent Name:</b>	MATTHEW I. BURTON
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<b>Address Line 2:</b>	P.O. BOX 1832
<b>Address Line 4:</b>	NEW HAVEN, CONNECTICUT 06508
<b>ATTORNEY DOCKET NUMBER:</b>	103749-2-300
<b>NAME OF SUBMITTER:</b>	MATTHEW I. BURTON
<b>SIGNATURE:</b>	/Matthew I Burton/
<b>DATE SIGNED:</b>	11/21/2017
<b>Total Attachments: 3</b>	
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ASSIGNMENT

WHEREAS, WE, Dror Hurwitz, residing at RM 3105, Building 1, no. 227, Shuiwan Road, Gongbei, Zhuhai, Guangdong Province, P.R. China; and Alex Huang, residing at Access Founder PCB Industry Park, Fushan Industry Zone, Qianwu Town, Doumen District, Zhuhai, P.R. China 519173; have invented certain new and useful improvements in INTERPOSER FRAME WITH POLYMER MATRIX AND METHODS OF FABRICATION for which we:

have filed an application for Letters Patent of the United States on May 5, 2014 under Serial No. 14/269,884; and

WHEREAS, Zhuhai Advanced Chip Carriers & Electronic Substrate Solutions Technologies Co. Ltd. organized under the laws of P.R. China, having its principal place of business at Founder PCB Industry Park, Qianwu, Doumen, Zhuhai, P.R. China 519173 is desirous of obtaining the entire right, title, and interest in, to and under the said improvements and the said application;

NOW, THEREFORE, in consideration of good and valuable consideration, the receipt of which is hereby acknowledged, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto Zhuhai Advanced Chip Carriers & Electronic Substrate Solutions Technologies Co. Ltd., its successors, legal representatives, and assigns the entire right, title, and interest in, to and under the improvements, and the application and all divisions, renewals, and continuations thereof, and all Letters Patents of the United States which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patents which may hereafter be filed for the improvements in any country or countries foreign to the United States, and all Letters Patents which may be granted for the improvements in any country or countries foreign to the United States and all extensions, renewals, and reissues thereof; and we hereby authorize and request the Commissioner of Patents of the United States and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on

applications as aforesaid, to issue all Letters Patent for said improvement to Zhuhai Advanced Chip Carriers & Electronic Substrate Solutions Technologies Co. Ltd., its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to Zhuhai Advanced Chip Carriers & Electronic Substrate Solutions Technologies Co. Ltd., its successors, legal representatives and assigns, any facts known to us respecting the improvements, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing and reissue applications, make all rightful oaths, and generally do everything possible to aid Zhuhai Advanced Chip Carriers & Electronic Substrate Solutions Technologies Co. Ltd., its successors, legal representatives and assigns to obtain and enforce proper patent protection for the improvements in all countries.

AND WE HEREBY further assign and transfer to Zhuhai Advanced Chip Carriers & Electronic Substrate Solutions Technologies Co. Ltd. all priority rights derived from such application therefore by virtue of the International Convention for the Protection of Industrial Property for any and all member countries of the aforesaid International convention and we do hereby assign and transfer to Zhuhai Advanced Chip Carriers & Electronic Substrate Solutions Technologies Co. Ltd. the sole right to file further applications for patents under the patent laws of any country of the world based on any improvements disclosed in said application as fully and entirely as the same would have been held by us had this assignment not been made.

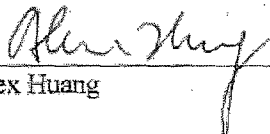
AND WE AUTHORIZE the law firm of Wiggin and Dana LLP to add to this Assignment the filing date and serial number of the patent application prior to recordation of this Assignment.

IN TESTIMONY WHEREOF, we hereunto set our hand the day and year set opposite our respective signature.

Date: June 5th, 2014

  
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Dror Huzwitz

Date: June 5th, 2014

  
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Alex Huang